

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	09538684
<b>Filing Date:</b>	30-Mar-2000
<b>Title of Invention:</b>	Varied-thickness heat sink for integrated circuit (ic) package
First Named Inventor/Applicant Name:	Larry D. Kinsman
<b>Filer:</b>	James R. Duzan/Debra Mitchell
<b>Attorney Docket Number:</b>	3056.1US (96-803.1)

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Notice of appeal	1401	1	500	500

Post-Allowance-and-Post-Issuance:

**Extension-of-Time:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>500</b>